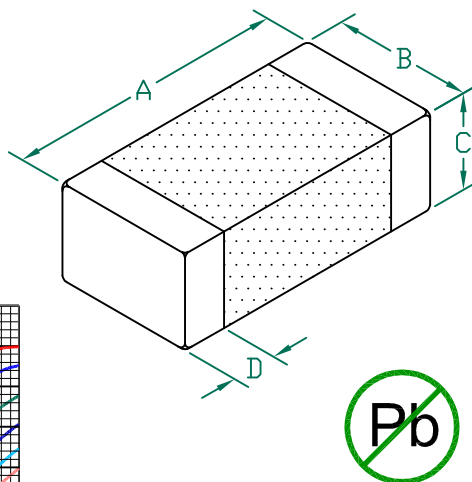


HI1206T500R-10

**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	3.20 [.126]	+0.20 [.008]
B	1.60 [.063]	+0.20 [.008]
C	1.10 [.043]	+0.20 [.008]
D	0.51 [.020]	+0.25 [.010]



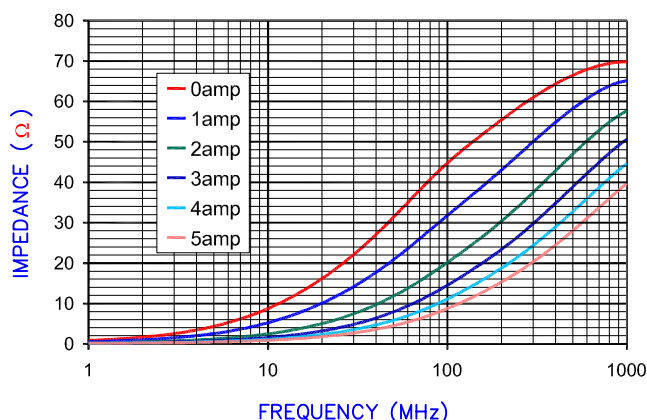
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	50	
Minimum	38	
Maximum	63	0.010 6000 mA

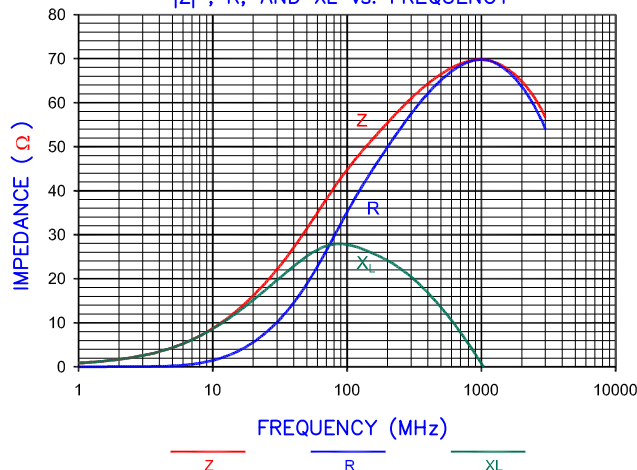
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. TERMINATION FINISH IS 100% TIN.
4. OPERATEING TEMPERATURE TEMP: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (INCLUDING SELF-HEATING)

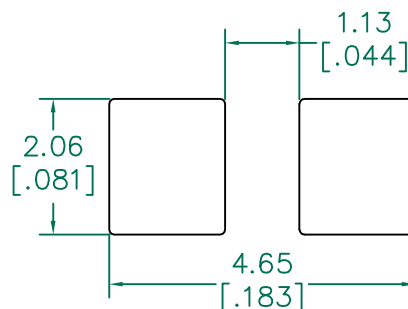
Z vs. FREQUENCY
IMPEDANCE UNDER DC BIAS



|Z|, R, AND XL vs. FREQUENCY

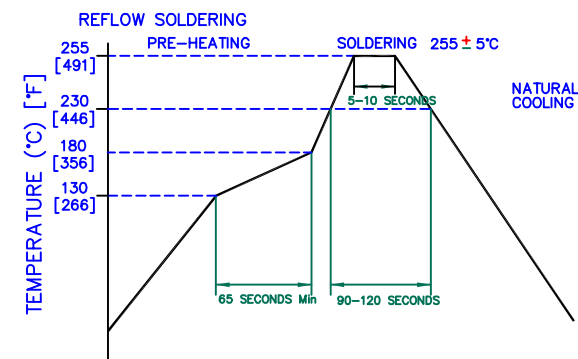


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
D	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	PROJECT/PART NUMBER: HI1206T500R-10			
C	UPDATE COMPANY LOGO & ROHS SYM.	01/17/08	JRK				
B	ADD ROHS SYMBOL AND NOTE 3	10/01/04	JRK				
A	ORIGINAL DRAFT	03/02/04	JRK				
REV	DESCRIPTION	DATE	INT	DATE: 03/02/04	SCALE: NTS	SHEET: 2 of 2	